

*Supplementary information*

**Preparation of graphene/copper composite with thiophenol molecular junction  
for thermal conductive application**

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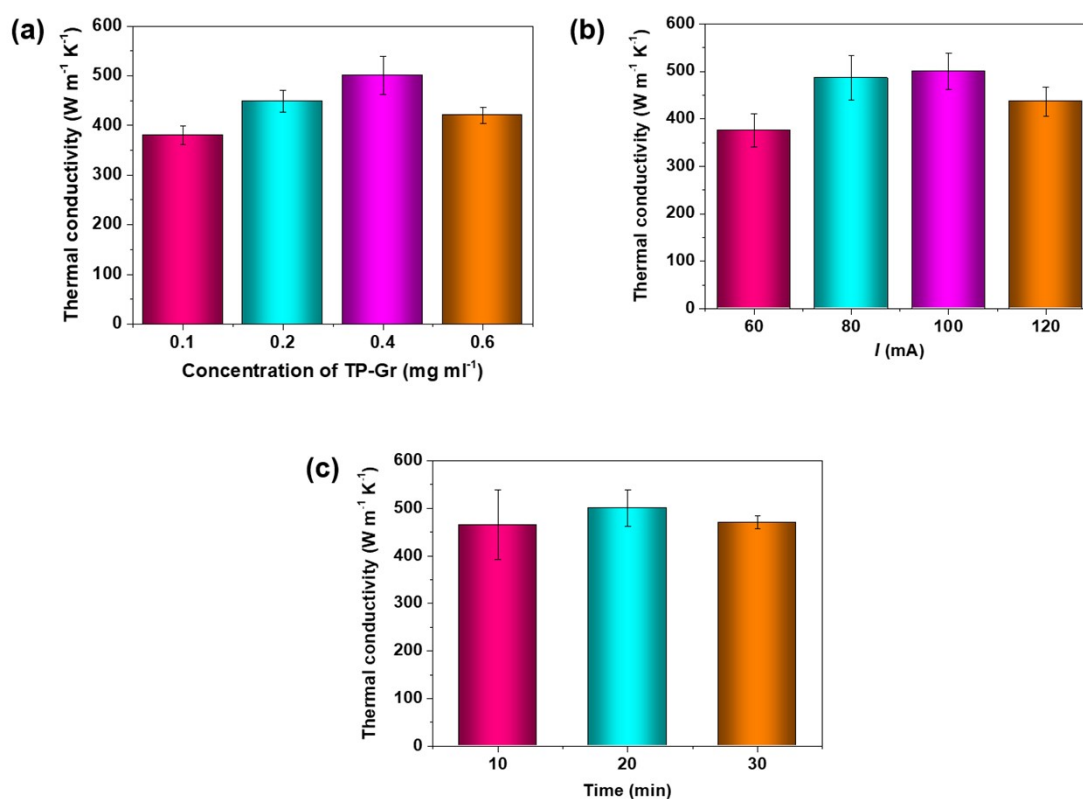
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**Fig. S1.** Effect of (a) TP-Gr concentration, (b) current, (c) electroplating time and (d) temperature on the thermal conductivity.